

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

Assignment ID: PATI503677

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT	
<b>CONVEYING PARTY DATA</b>		
<b>Name</b>		<b>Execution Date</b>
Chigma Technology		09/13/2024
<b>RECEIVING PARTY DATA</b>		
<b>Company Name:</b>	Chengdu Xinsheng Integrated Circuit Co., Ltd.	
<b>Street Address:</b>	23rd Floor, Building 1, No. 999 Xincheng Avenue	
<b>Internal Address:</b>	Chengdu High tech Zone, Pilot Free Trade Zone	
<b>City:</b>	Chengdu, Sichuan	
<b>State/Country:</b>	CHINA	
<b>PROPERTY NUMBERS Total: 9</b>		
<b>Property Type</b>	<b>Number</b>	
Patent Number:	10374631	
Patent Number:	10419026	
Patent Number:	10452871	
Patent Number:	10476524	
Patent Number:	10489291	
Patent Number:	10509600	
Patent Number:	10509698	
Patent Number:	10606697	
Patent Number:	10671313	
<b>CORRESPONDENCE DATA</b>		
<b>Fax Number:</b>		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
<b>Phone:</b>	(408)286-8933	
<b>Email:</b>	pt_docket@iplg.com	
<b>Correspondent Name:</b>	Alexaray Martinez	
<b>Address Line 1:</b>	1871 The Alameda	
<b>Address Line 2:</b>	Suite 250	
<b>Address Line 4:</b>	San Jose, CALIFORNIA 95126	
<b>ATTORNEY DOCKET NUMBER:</b>	CHIGMA	
<b>NAME OF SUBMITTER:</b>	AlexaRay Martinez	

PATENT

<b>SIGNATURE:</b>	AlexaRay Martinez
<b>DATE SIGNED:</b>	09/18/2024
	This document serves as an Oath/Declaration (37 CFR 1.63).
<b>Total Attachments: 2</b> source=Assignment#page1.tiff source=Assignment#page2.tiff	

## ASSIGNMENT

**WHEREAS, Chigma Technology** (hereinafter referred to as "ASSIGNOR"), having its principle business place at 4655 Old Ironsides Drive, Suite 350, Santa Clara, CA, 95054, is the owner of the following United States Letter Patents:

United States Letters Patent No. 10,374,631, issued on August 06, 2019 for the invention entitled "**LOOK-AHEAD LDPC DECODER**",

United States Letters Patent No. 10,419,026, issued on September 17, 2019 for the invention entitled "**METHOD AND APPARATUS FOR EFFICIENT DATA DECODING**",

United States Letters Patent No. 10,452,871, issued on October 22, 2019 for the invention entitled "**METHOD AND APPARATUS FOR DATA ENCRYPTION USING STANDARDIZED DATA STORAGE AND RETRIEVAL PROTOCOL**",

United States Letters Patent No. 10,476,524, issued on November 12, 2019 for the invention entitled "**METHOD AND APPARATUS FOR EFFICIENT DATA DECODING**",

United States Letters Patent No. 10,489,291, issued on November 26, 2019 for the invention entitled "**GARBAGE COLLECTION METHOD FOR A DATA STORAGE APPARATUS BY FINDING AND CLEANING A VICTIM BLOCK**",

United States Letters Patent No. 10,509,600, issued on December 17, 2019 for the invention entitled "**METHOD AND APPARATUS FOR DATA COMPRESSION AND DECOMPRESSION USING A STANDARDIZED DATA STORAGE AND RETRIEVAL PROTOCOL**",

United States Letters Patent No. 10,509,698, issued on December 17, 2019 for the invention entitled "**METHOD AND APPARATUS FOR DATA ENCODING AND DECODING USING A STANDARDIZED DATA STORAGE AND RETRIEVAL PROTOCOL**",

United States Letters Patent No. 10,606,697, issued on March 31, 2020 for the invention entitled "**METHOD AND APPARATUS FOR IMPROVED DATA RECOVERY IN DATA STORAGE SYSTEMS**"; and

United States Letters Patent No. 10,671,313, issued on June 2, 2020 for the invention entitled "**APPARATUS AND METHODS FOR FAST AND SECURE STORAGE OF DATA**";

**WHEREAS, Chengdu Xinsheng Integrated Circuit Co., Ltd.** (hereinafter referred to as "ASSIGNEE"), a corporation organized and existing under the laws of China, having its principal place of business at 23rd Floor, Building 1, No. 999 Xincheng Avenue, Chengdu High tech Zone, China (Sichuan) Pilot Free Trade Zone, is desirous of acquiring the entire right, title and interest in and to the inventions and said Letters Patents;

**NOW THEREFORE**, for and in consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, said ASSIGNOR, has sold, assigned and set over, and by these presents does hereby sell, assign and set over unto the said ASSIGNEE, its legal representatives, successors and assigns, its entire rights, title and interest in and to said United States Letters Patents, and the inventions disclosed, described or claimed in said Letters Patents, together with all divisions, reissues, continuations and extensions thereof, and any and all rights of recovery for past infringement of said Letters Patents.

ASSIGNOR also hereby sells and assigns to said ASSIGNEE, its successors, assigns and legal representatives the full and exclusive rights, title and interest to the inventions disclosed in said patents and any applications throughout the world, including the right to file applications and obtain patents, utility models, industrial models and designs for said inventions in its own name throughout the world including all rights of priority, all rights to publish cautionary notices reserving ownership of said inventions and all rights to register said inventions in appropriate registries; and

ASSIGNOR further agrees to execute any and all powers of attorney, applications, assignments, declarations, affidavits, and any other papers in connection therewith necessary to perfect such rights, title and interest in ASSIGNEE, its successors, assigns and legal representatives.

ASSIGNOR hereby further agrees that ASSIGNOR will communicate to said ASSIGNEE, or its successors, assigns and legal representatives, any facts known to ASSIGNOR respecting any improvements; and, at the expense of said ASSIGNEE, to testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, continuation-in-part, reissue and substitute applications, make all lawful oaths, and generally do everything possible to vest title in said ASSIGNEE and to aid said ASSIGNEE, its successors, assigns and legal representatives to obtain and enforce proper protection for said inventions in all countries.

9/13/2024

Date: \_\_\_\_\_

DocuSigned by:

*Po-Chien Chang*

D55BFF1FC7994C0...

Signature: \_\_\_\_\_

Name: Po-Chien Chang

Title: CEO

Chigma Technology